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(54) Title: MICROELECTROMECHANICAL SYSTEM (MEMS) BOND RELEASE STRUCTURE AND METHOD OF WAFER
TRANSFER FOR THREE-DIMENSIONAL INTEGRATED CIRCUIT (3D IC) INTEGRATION

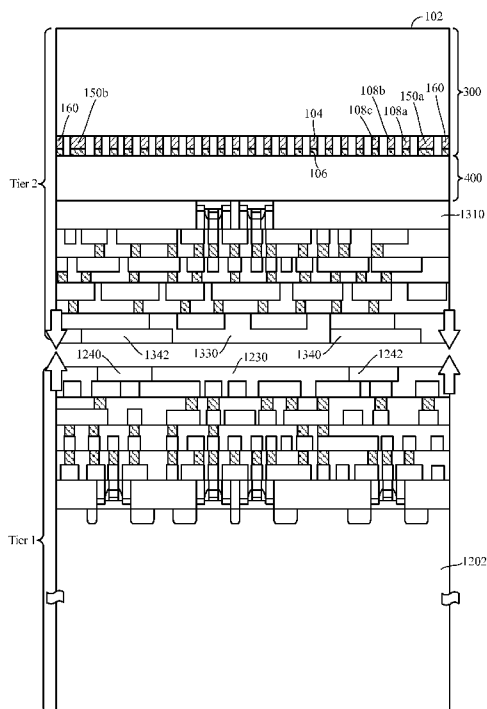


FIG. 14

(57) Abstract: A microelectromechanical system (MEMS) bond release structure is provided for manufacturing of three-dimensional integrated circuit (3D IC) devices with two or more tiers. The MEMS bond release structure includes a MEMS sacrificial release layer which may have a pillar or post structure, or alternatively, a continuous sacrificial layer for bonding and release.



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- *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))*

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